

N-Channel Power MOSFET

600V, 0.6A, 5Ω

FEATURES

- Robust high voltage termination
- Avalanche energy specified
- Diode is characterized for use in bridge circuits
- Source to Drain diode recovery time comparable to a discrete fast recovery diode.

KEY PERFORMANCE PARAMETERS

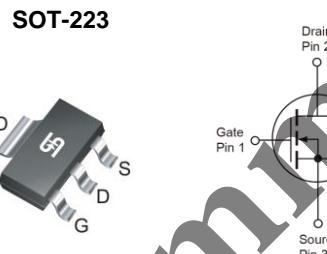
PARAMETER	VALUE	UNIT
V_{DS}	600	V
$R_{DS(on)}$ (max)	5	Ω
Q_g	13	nC

APPLICATION

- Power Supply
- Lighting
- Charger



RoHS
COMPLIANT
HALOGEN
FREE



Notes: MSL 3 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current (Note 1)	I_D	0.6	A
		0.36	
Pulsed Drain Current (Note 2)	I_{DM}	1.5	A
Total Power Dissipation @ T _C = 25°C	P_{DTOT}	2.5	W
Single Pulsed Avalanche Energy (Note 3)	E_{AS}	62	mJ
Single Pulsed Avalanche Current (Note 3)	I_{AS}	2.5	A
Operating Junction Temperature	T_J	150	°C
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Case Thermal Resistance	$R_{\theta JC}$	15	°C/W
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	55.8	°C/W

Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4 PCB with minimum recommended footprint in still air

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ C$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static ^(Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	600	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(TH)}$	2	--	4	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	I_{DSS}	--	--	1	μA
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 0.6A$	$R_{DS(ON)}$	--	3.6	5	Ω
Forward Transconductance	$V_{DS} = 10V, I_D = 0.2A$	g_{fs}	--	0.8	--	S
Dynamic ^(Note 5)						
Total Gate Charge	$V_{DS} = 400V, I_D = 0.6A, V_{GS} = 10V$	Q_g	--	13	--	nC
Gate-Source Charge		Q_{gs}	--	2	--	
Gate-Drain Charge		Q_{gd}	--	6	--	
Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	C_{iss}	--	435	--	pF
Output Capacitance		C_{oss}	--	56	--	
Reverse Transfer Capacitance		C_{rss}	--	9.2	--	
Switching ^(Note 6)						
Turn-On Delay Time	$V_{GS} = 10V, I_D = 0.6A, V_{DD} = 300V, R_G = 18\Omega$	$t_{d(on)}$	--	12	--	ns
Turn-On Rise Time		t_r	--	21	--	
Turn-Off Delay Time		$t_{d(off)}$	--	30	--	
Turn-Off Fall Time		t_f	--	24	--	
Source-Drain Diode ^(Note 4)						
Forward On Voltage	$I_S = 0.6A, V_{GS} = 0V$	V_{SD}	--	0.85	1.15	V

Notes:

1. Current limited by package
2. Pulse width limited by the maximum junction temperature
3. $L = 20mH, I_{AS} = 2.5A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^\circ C$
4. Pulse test: $PW \leq 300\mu s$, duty cycle $\leq 2\%$
5. For DESIGN AID ONLY, not subject to production testing.
6. Switching time is essentially independent of operating temperature.

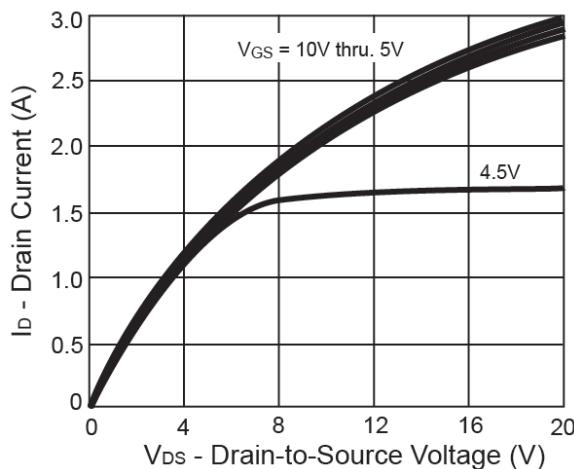
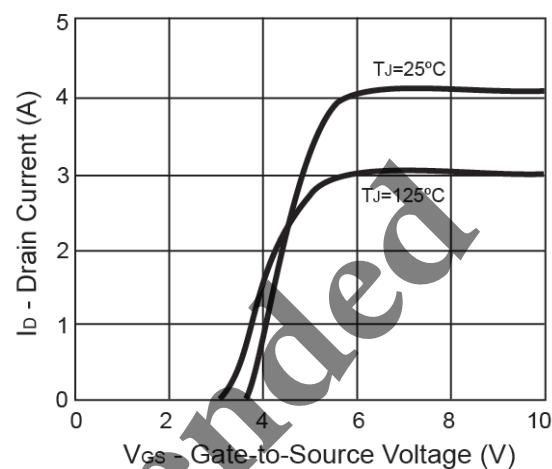
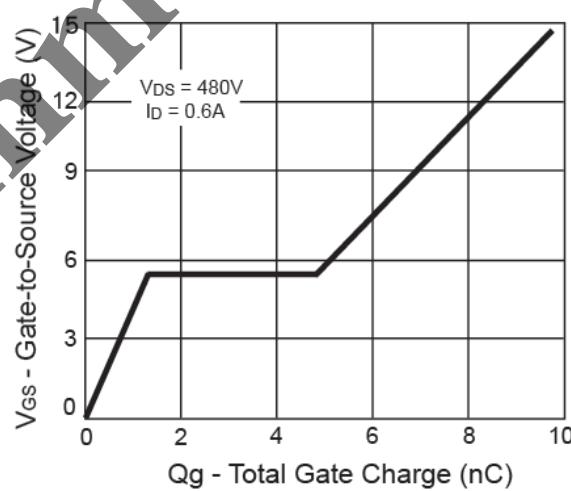
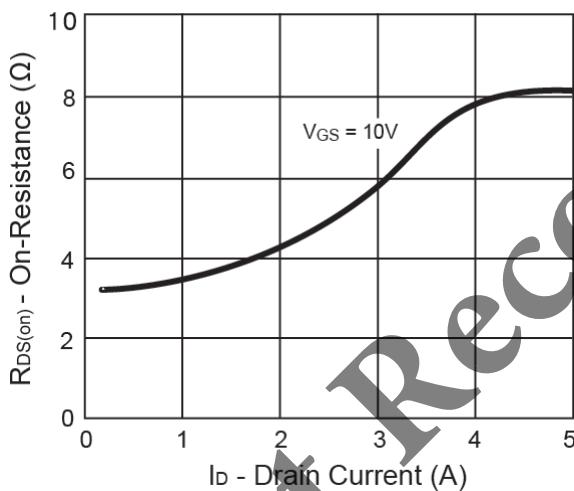
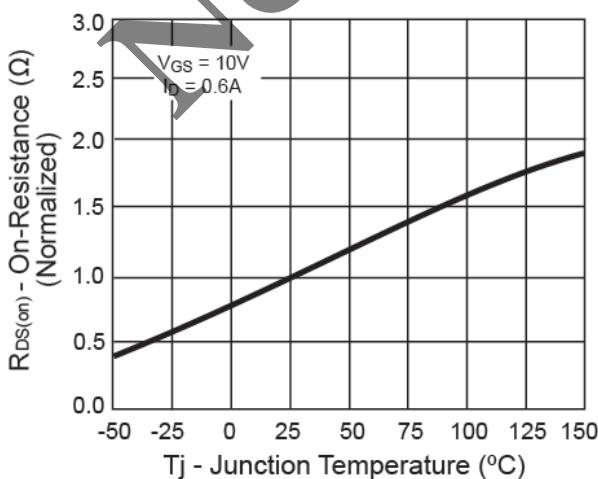
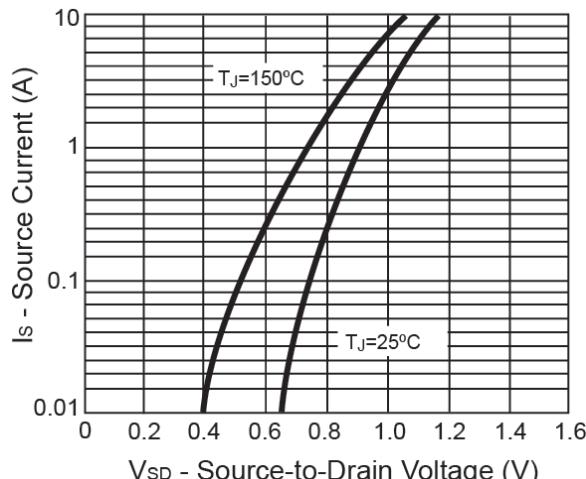
ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM2N60SCW RPG	SOT-223	2,500pcs / 13" Reel

Note:

1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
2. Halogen-free according to IEC 61249-2-21 definition

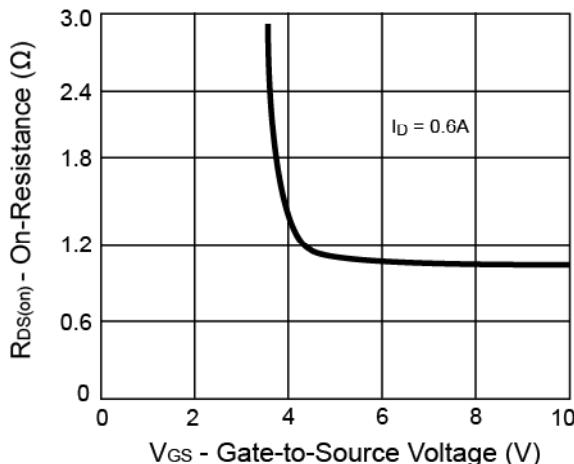
Not Recommended

CHARACTERISTICS CURVES
 $(T_C = 25^\circ\text{C} \text{ unless otherwise noted})$
Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current

On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage


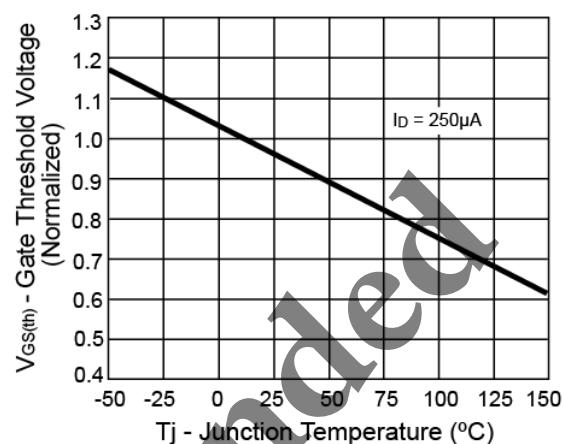
CHARACTERISTICS CURVES

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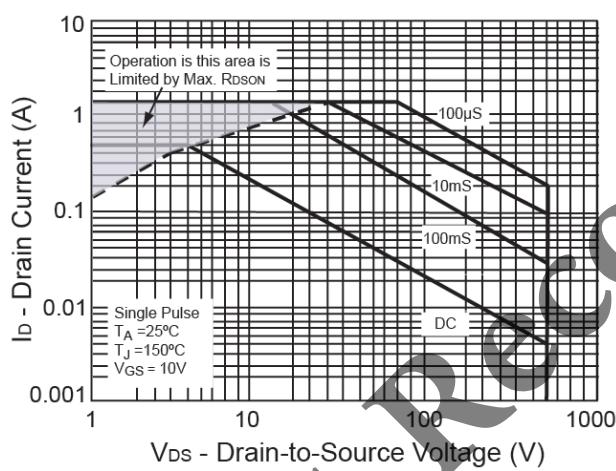
On-Resistance vs. Gate-Source Voltage



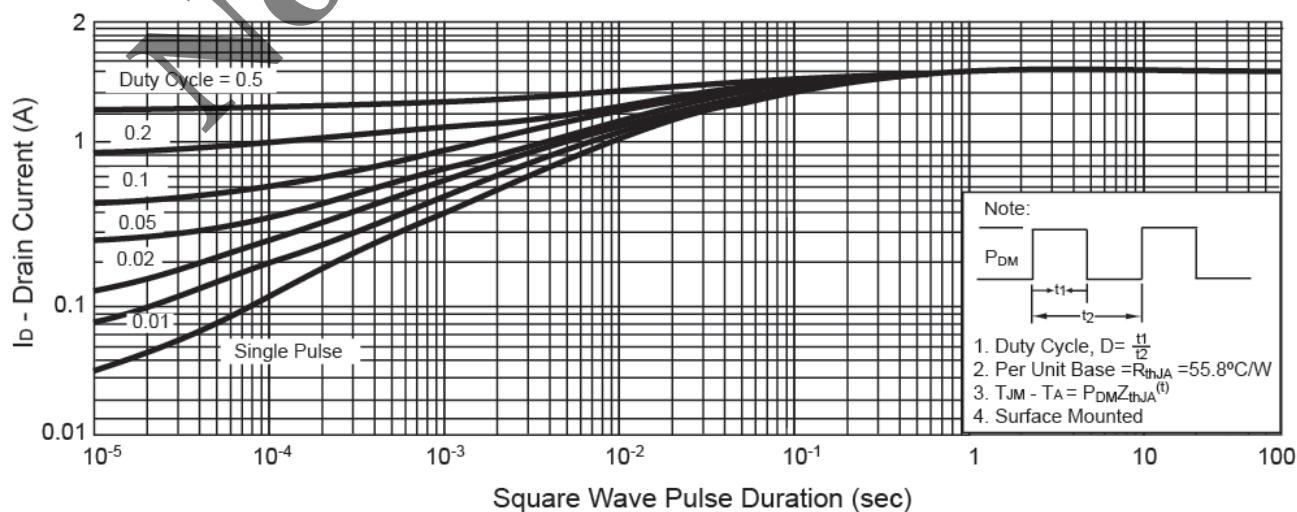
Threshold Voltage

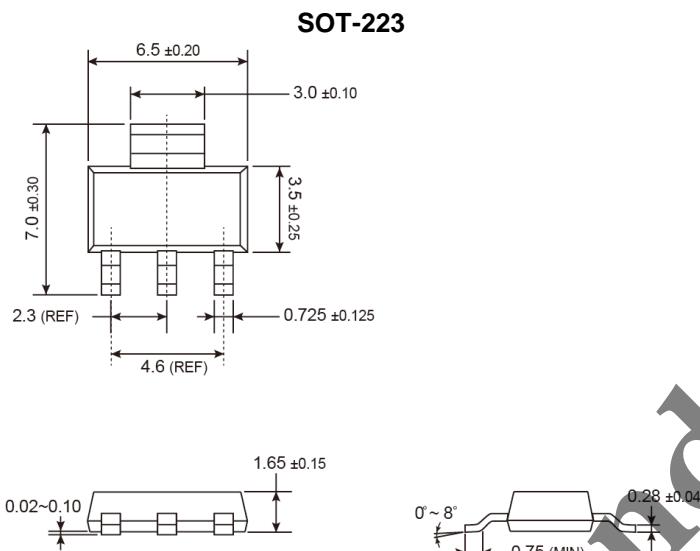
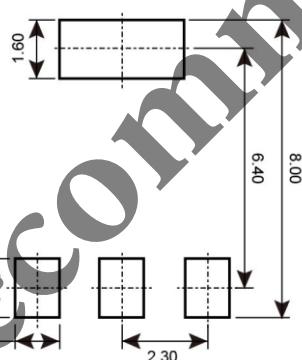
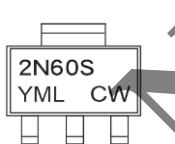


Maximum Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

SUGGESTED PAD LAYOUT

MARKING DIAGRAM


Y = Year Code

M = Month Code for Halogen Free Product

O =Jan **P** =Feb **Q** =Mar **R** =Apr

S =May **T** =Jun **U** =Jul **V** =Aug

W =Sep **X** =Oct **Y** =Nov **Z** =Dec

L = Lot Code (1~9, A~Z)

Not Recommended

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